Martin Hirman

List of Publications by Year
in descending order

Source: https://exaly.com/author-pdf/10047669/publications.pdf

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38	176	5	8
papers	citations	h-index	g-index

1684188 1588992

38	38	38	113
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	Influence of Sweat on Joint and Sensor Reliability of E-Textiles. Energies, 2022, 15, 506.	3.1	7
2	Higher Temperature Washing of Electrically Connected SMD Components onto the Textile Ribbons. , 2022, , .		0
3	Alternative interconnection methods for bare die electronic components. , 2022, , .		0
4	Properties Verification of Improved Lead-free Solder Alloys. , 2021, , .		2
5	Reliability of Glued SMD Components on Smart Textile. , 2020, , .		1
6	Design, Fabrication and Risk Assessment of IoT Unit for Products Manufactured in Industry 4.0 Factory. Procedia Manufacturing, 2020, 51, 1178-1183.	1.9	4
7	Comparison of Conductive Ribbons Reliability during Electrical Current Ageing. , 2020, , .		0
8	Electrical Resistance of Solder Joints on Conductive Ribbons. , 2020, , .		2
9	Optimization of Contacting Technological Process on Printed Conductive Pattern for Wearable Electronics. , 2020, , .		1
10	Effects of Accelerated Climatic Aging on Volume and Surface Resistivity of Glass Fiber Reinforced Thermoset Composites. , 2020, , .		2
11	Influence of production and operating conditions on properties of acrylic conformal coatings. , 2020, , .		0
12	Effect of Washing Cycles on Glued Conductive Joints Used on Stretchable Smart Textile Ribbons. , 2020, , .		6
13	Alternative technology for SMD components connection by non-conductive adhesive on a flexible substrate. Journal of Materials Science: Materials in Electronics, 2019, 30, 14214-14223.	2.2	6
14	Relationship of Soldering Profile, Voids Formation and Strength of Soldered Joints. , 2019, , .		10
15	Reliability of Glued Joints on Flexible Substrates During Accelerated Current Ageing. , 2019, , .		3
16	Comparison of QFN Chips Glued by ACA and NCA Adhesives on the Flexible Substrate. , 2019, , .		3
17	Bend Testing of SMD Chip Resistors Glued on Flexible Substrates. , 2019, , .		1
18	The Testing of Brass Solderability for Hybrid Sewing Thread. , 2019, , .		4

#	Article	IF	Citations
19	Project Management during the Industry 4.0 Implementation with Risk Factor Analysis. Procedia Manufacturing, 2019, 38, 1181-1188.	1.9	24
20	Determination of Changes in Process Management within Industry 4.0. Procedia Manufacturing, 2019, 38, 1691-1696.	1.9	18
21	Influence of Increased Voltage on the Characteristics of Printed Circuit Board Protective Coatings. , 2018, , .		0
22	Current trends in the management of diagnostic processes in testing laboratories. , 2018, , .		0
23	SMD Components Assembly on a Flexible Substrate by Non-Conductive Adhesives. , 2018, , .		5
24	Optimization of Soldering Process to Reduce Contamination and Related Consequences. , 2018, , .		2
25	Analysis of Education Requirements for Electronics Manufacturing within Concept Industry 4.0. , 2018, , .		9
26	Optimization of solder paste quantity considering the properties of solder joints. Soldering and Surface Mount Technology, 2017, 29, 15-22.	1.5	26
27	Comparison of the characteristics of PCB protective coatings. , 2017, , .		3
28	Comparison of copper and silver thick film on alumina substrates properties. , 2017, , .		1
29	Nanoparticle based ink printed chip interconnections. , 2017, , .		2
30	Influence of flexible substrate roughness with aerosol jet printed pads on the mechanical shear strength of glued joints. , 2017, , .		2
31	Shear Strength of Conductive Adhesive Joints on Rigid and Flexible Substrates Depending on Adhesive Quantity. Journal of Electrical Engineering, 2016, 67, 177-184.	0.7	1
32	Properties of temperature stable solder pastes. , 2016, , .		0
33	Adhesion improvement of Thick Printed Copper film on alumina substrates by controlling of oxygen level in furnace. , 2016, , .		8
34	Influence of electrically conductive adhesive quantity on insulation distance and shear strength of glued joints. , 2016, , .		1
35	Methodologies to Improve Experimental Research Processes in Soldering Technology. Periodica Polytechnica Electrical Engineering and Computer Science, 2016, 60, 237-244.	1.0	1
36	A comparison of the shear strength of conductive adhesives and soldering alloys. , 2015, , .		4

#	Article	IF	Citations
37	Influence of reflow soldering profiles on creation of IMC at the interface of SnBi/Cu. , 2014, , .		14
38	Study of low-temperature interconnection techniques for instant assembly of electronics on stretchable e-textile ribbons. Textile Reseach Journal, 0, , 004051752210847.	2.2	3